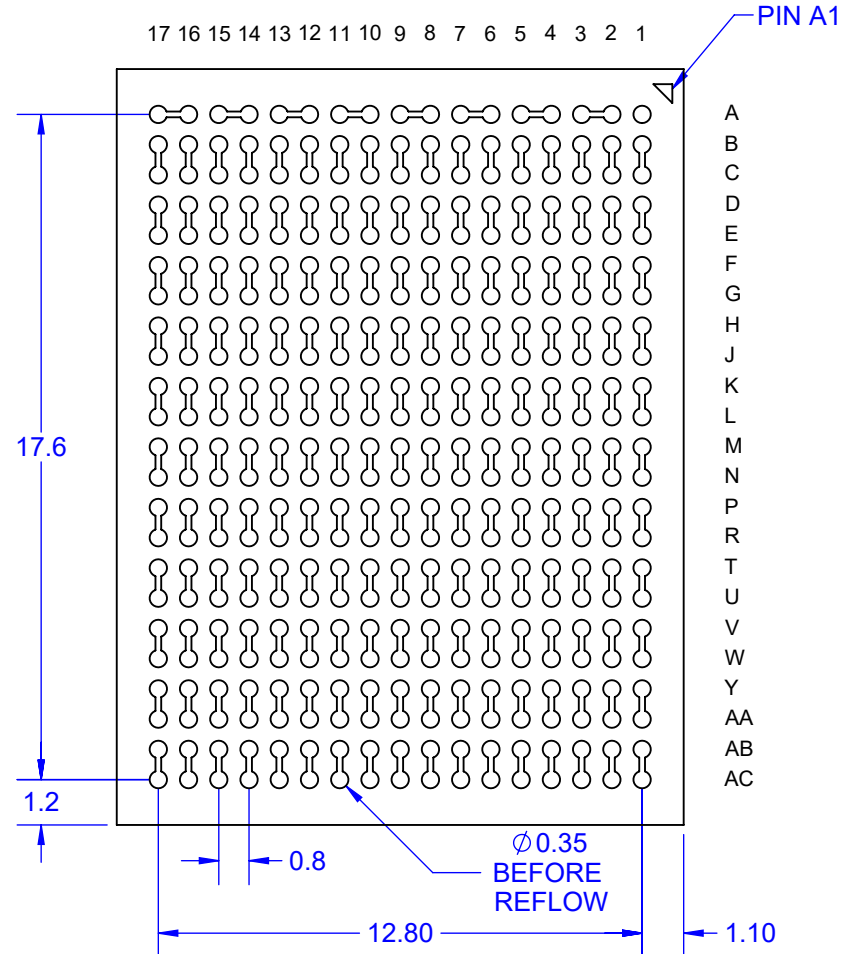
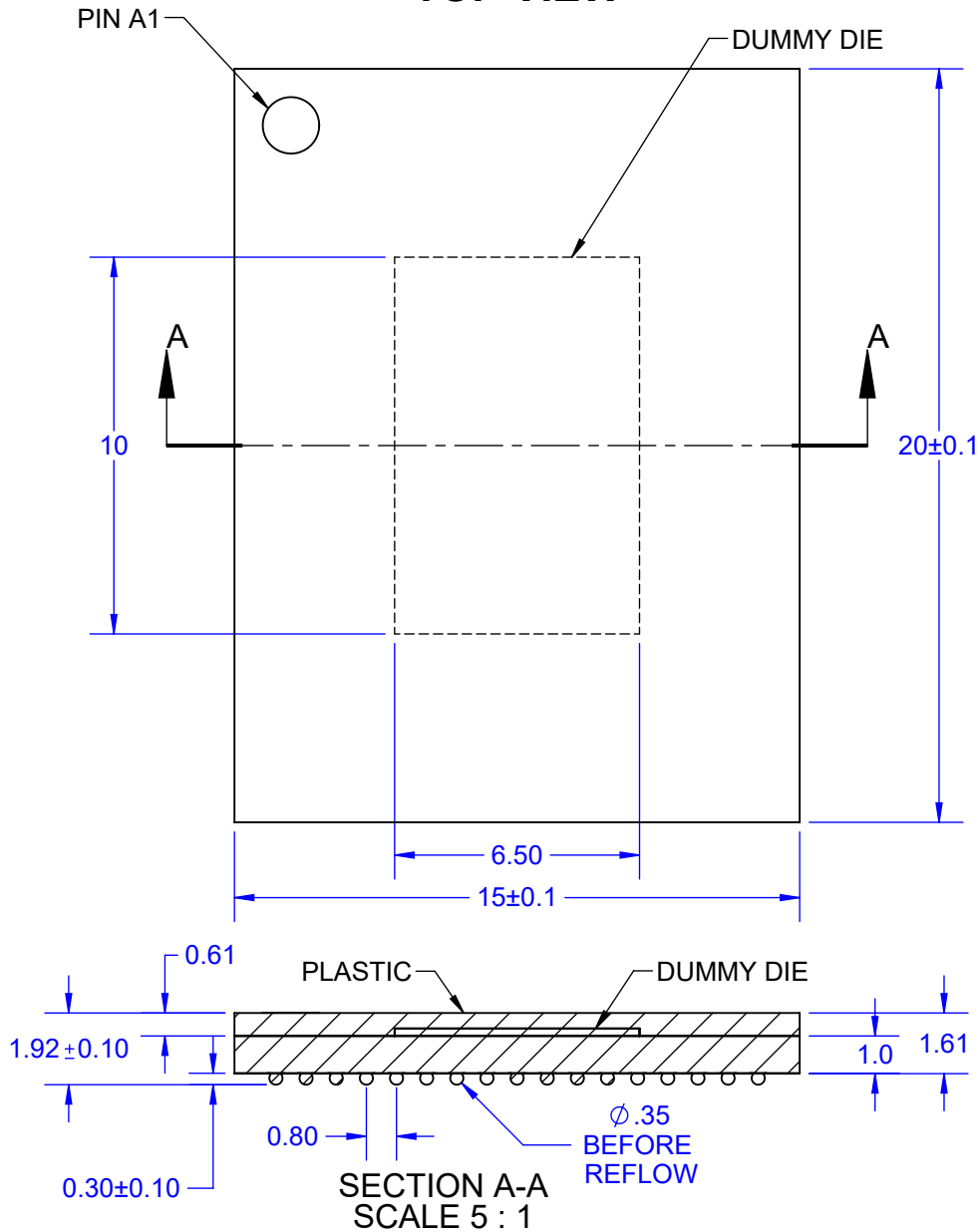


TOP VIEW

BALL VIEW



Notes: (Unless Otherwise Specified).

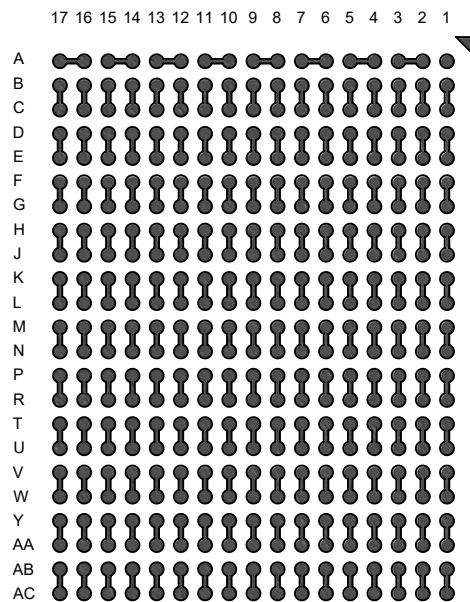
- DIMENSIONS: MM.
- SOLDER BALL ALLOY: SEE PART NUMBER TABLE.
- BALL DIAMETER (BEFORE REFLOW): 0.35mm (13.8mil).
- SOLDER MASK DEFINED PAD OPENING: 0.30mm (11.8mil).
- PAD MATERIAL: PAD Cu DIAMETER 0.46mm (18mil).
- SUBSTRATE MATERIAL: BT.
- DUMMY DIE: SIZE OPTIONAL.
- DAISY CHAIN PATTERN (SEE PAGE 2).
- MSL-3 RECOMMEND BAKING 24 HOURS @125°C TO REMOVE MOISTURE PRIOR TO SOLDERING TO PC BOARD.

PART NUMBER TABLE

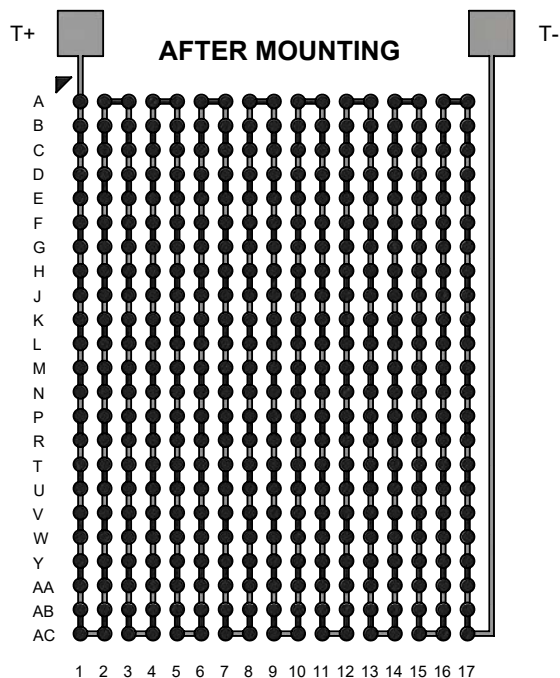
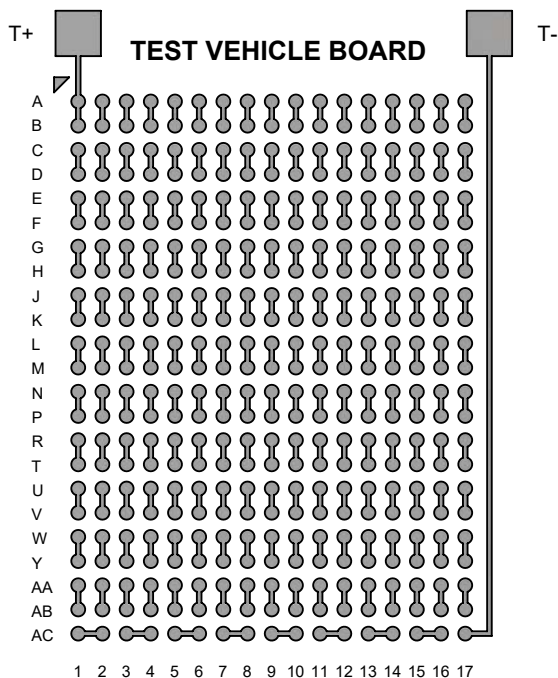
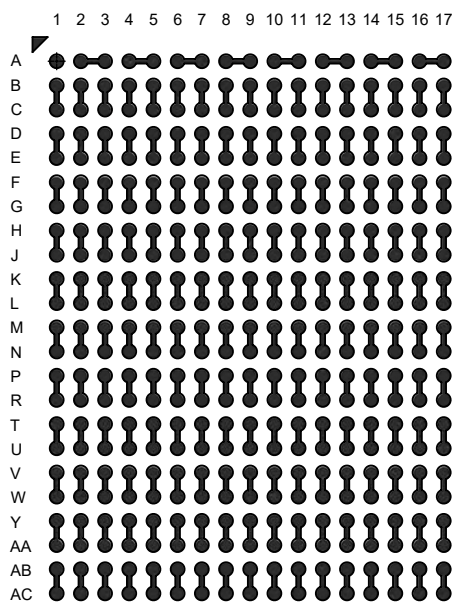
PART NUMBER	BALL ALLOY	Pb-FREE	RoHS	Si DIE
BGA391T.8C-DC923D	SAC305	YES	YES	NO
BGA391T.8-DC923D	SnPb	NO	NO	NO

APPROVALS	DATE			
DRAWN T. Au	8/18/2023			
ENG M. Hart	8/18/2023	TITLE BGA391T.8C-DC923D DAISY CHAIN BGA		
MFG		SCALE 5:1	SIZE A	DRAWING NO. 589230
QA				REV A
CUST				
REVISED		DO NOT SCALE DRAWING		SHEET 1 OF 3

BALL VIEW



BOTTOM SIDE (TOP X-RAY VIEW)



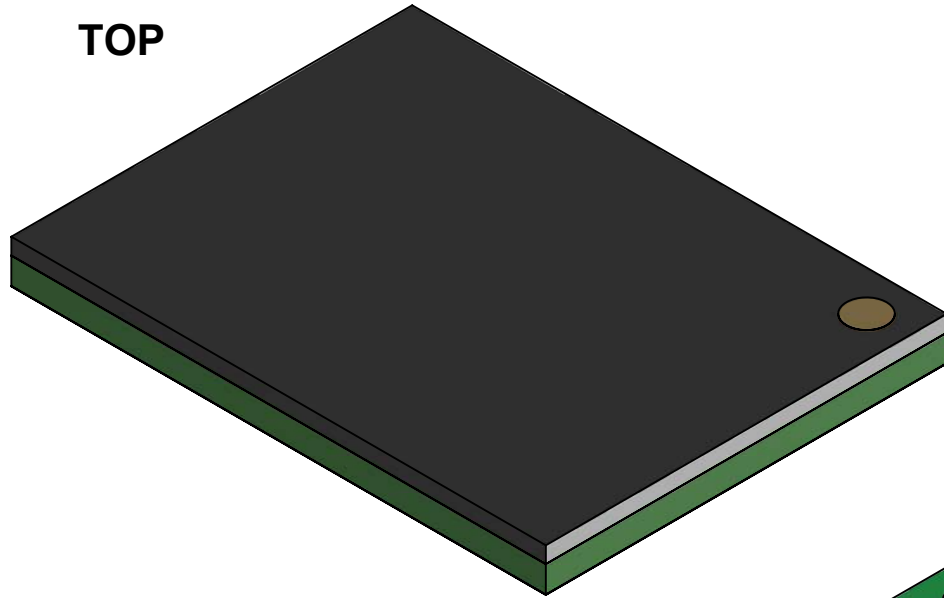
Notes: (Unless Otherwise Specified)

1. PCB BOARD DIMENSIONS ARE PRESENTED ONLY AS A GUIDELINE. DESIGNERS SHOULD USE THEIR OWN EXPERIENCE WHEN DESIGNING PCB.

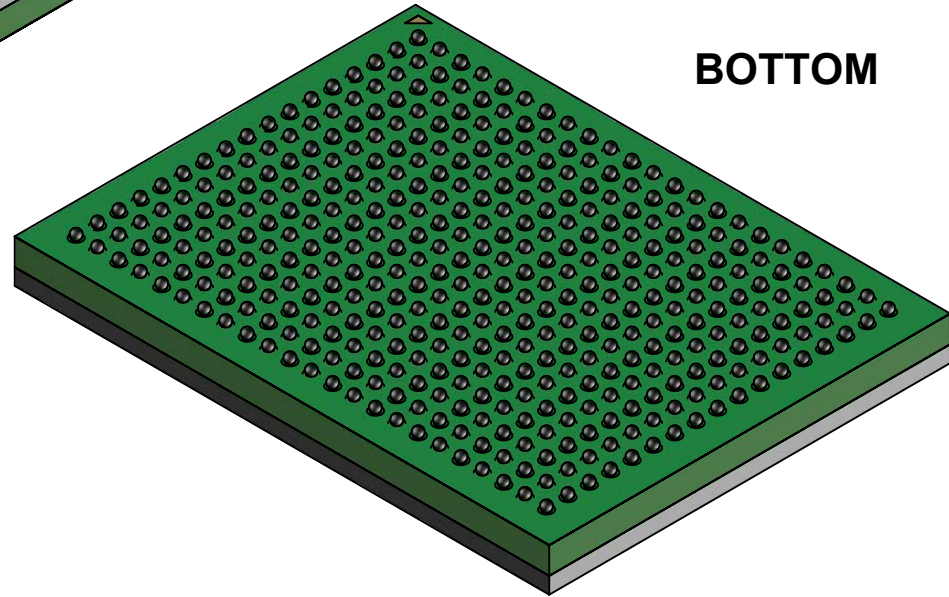
TopLine[®]			
TITLE		BGA391T.8C-DC923D DAISY CHAIN BGA	
SCALE	SIZE	DRAWING NO.	REV
4:1	A	589230	A
DO NOT SCALE DRAWING			SHEET 2 OF 3

MODEL WITH SOLDER BALLS

TOP



BOTTOM



TopLine[®]

TITLE BGA391T.8C-DC923D
DAISY CHAIN BGA

SCALE	SIZE	DRAWING NO.	REV
5:1	A	589230	A

DO NOT SCALE DRAWING

SHEET 3 OF 3